

AMENDMENTS TO THE CLAIMS:

This listing of claims replaces all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

1. (Currently Amended) An electronic component comprising containing:  
[[ - ] a multi-layer substrate having an upper side and under side, the multi-layer substrate comprising at least one integrated impedance converter; and (MS);  
[[ - ] at least one chip component (CB) having comprising external contacts (AE),  
wherein the at least one chip component (CB) is being disposed on the upper side of the multi-layer substrate, (MS), characterized in that at least one integrated impedance converter (IW) is disposed in the multi-layer substrate (MS), wherein the at least one chip component (CB) is being electrically connected with to the at least one integrated impedance converter (IW).
2. (Currently Amended) The electronic component according to of claim 1,  
wherein in which the external contacts (AE) of the at least one chip component (CB)  
constitute SMD comprise surface mounted device contacts.
3. (Currently Amended) The electronic component according to of claim 1 or 2, in  
which wherein the multi-layer substrate (MS) comprises, in addition to the impedance

~~converter~~, at least one ~~additional integrated~~ passive circuit element or at least one active circuit element.

4. (Currently Amended) The electronic component according to of claim 1 ~~at least one of claims 1 to 3, in which~~ wherein the at least one chip component (CB) comprises at least one filter circuit.

5. (Currently Amended) The electronic component according to of claim 1 ~~at least one of claims 1 to 4, in which~~ wherein the at least one chip component (CB) comprises at least one resonator ~~operating~~ that operates with surface acoustic waves.

6. (Currently Amended) The electronic component according to of claim 1 ~~at least one of claims 1 to 5, in which~~ wherein the at least one chip component (CB) comprises a resonator ~~operating~~ that operates with bulk acoustic waves.

7. (Currently Amended) The electronic component according to of claim 1 ~~at least one of claims 1 to 6, in which~~ wherein the at least one chip component (CB) ~~is~~ comprises a microwave ceramic filter.

8. (Currently Amended) The electronic component according to of claim 1 ~~at least one of claims 1 to 7, in which~~ wherein the at least one chip component (CB) ~~is~~ comprises an ~~LC~~ inductive-capacitive (LC) chip filter.

9. (Currently Amended) The electronic component according to of claim 1 ~~at least one of claims 1 to 8, in which~~ wherein the at least one chip component (CB) ~~is~~ comprises a stripline filter.

10. (Currently Amended) The electronic component according to of claim 1 ~~at least one of claims 1 to 9, in which~~ further comprising:

at least one discrete circuit element ~~passive or active circuit element~~ (SE) is disposed on the upper side of the multi-layer substrate, the at least one discrete circuit element comprising an active circuit element or a passive circuit element (MS).

11. (Currently Amended) The electronic component according to of claim 10 ~~at least one of claims 1 to 10, wherein in which~~ the at least one discrete circuit element (SE) ~~disposed on the surface of the multi-layer substrate forms~~ comprises at least a part of one of the following: a high-frequency circuit, an adjustment circuit, an impedance converter, an antenna circuit, a diode circuit, a high-pass filter, a low-pass filter, a band-pass filter, a band elimination filter, a power amplifier, a diplexer, a duplexer, a coupler, a directional coupler, a memory element, a balun, and ~~or~~ a mixer.

12. (Currently Amended) The electronic component according to of claim 10 ~~at least one of claims 1 to 11, in which~~ wherein the at least one discrete circuit element (SE)

~~disposed on the surface of the multi-layer substrate forms~~ comprises at least a part of a high-frequency circuit, a duplexer or a diplexer[[],]; and

wherein ~~said~~ the at least one discrete circuit element ~~connects~~ assists in connecting the at least one chip component (~~CB~~) ~~with~~ to an antenna.

13. (Currently Amended) The electronic component according to of claim 1,  
further comprising:

at least one circuit element integrated in the multi-layer substrate;

~~at least one of claims 1 to 12, in which~~ wherein the at least one circuit element ~~integrated in the multi-layer substrate (MS) forms~~ comprises at least a part of one of the following: a high-~~frequency~~ frequency circuit, an adjustment circuit, an antenna circuit, a diode circuit, a high-pass filter, a low-pass filter, a band-pass filter, a band elimination filter, a power amplifier, a diplexer, a duplexer, a coupler, a directional coupler, a memory element, a balun, and ~~or~~ a mixer.

14. (Currently Amended) The electronic component according to of claim 13, in  
~~which~~ wherein at least a part of an adjustment circuit integrated in the multi-layer substrate is formed as one or more strip conductors on the upper side of the multi-layer substrate ~~for~~  
~~later fine tuning.~~

15. (Currently Amended) The electronic component according to of claim 1 at least one of claims 1 to 14, in which wherein the multi-layer substrate (MS) comprises a plurality of adjustment circuits.

16. (Currently Amended) The electronic component according to of claim 1 at least one of claims 1 to 15, in which wherein the multi-layer substrate comprises (MS) ~~contains~~ ceramic layers.

17. (Currently Amended) The electronic component according to of claim 1 at least one of claims 1 to 16, in which wherein the multi-layer substrate (MS) ~~contains~~ comprises layers of silicone or silicone oxide.

18. (Currently Amended) The electronic component according to of claim 1 at least one of claims 1 to 17, wherein in which the multi-layer substrate (MS) ~~contains~~ comprises one or more layers of an organic material, ~~such as plastic or laminate.~~

19. (Currently Amended) The electronic component according to of claim 1 at least one of claims 1 to 18, in which wherein the at least one chip component comprises one or more inputs and outputs; and

wherein at least one input and/or at least one output of the at least one chip component (CB) ~~is used to conduct~~ conducts an asymmetrical signal.

20. (Currently Amended) The electronic component according to of claim 1 at least one of claims 1 to 19, wherein the at least one chip component comprises one or more inputs and outputs; and

~~in which the~~ wherein at least one input and/or the at least one output of the at least one chip component (CB) ~~is used to conduct~~ conducts a symmetrical signal.

21. (Currently Amended) The electronic component according to of claim 1 at least one of claims 1 to 20, in which the connections wherein the at least one chip component comprises a connection to ground, the connection to ground being made via of the at least one chip component (CB) are connected with an adjustment circuit that is at least partially integrated in the multi-layer substrate; and against the reference ground of the overall component,

wherein ~~said the~~ the adjustment circuit comprises at least one of ~~element selected from among~~ a coil, a capacitor ~~or~~ and a conductor line segment.

22. (Currently Amended) The electronic component according to of claim 10 at least one of claims 1 to 21, in which both wherein the at least one chip component (CB) and the at least one discrete circuit element comprise (SE) disposed on the upper side of the multi-layer substrate (MS) constitute SMD elements (surface mounted design elements).

23. (Currently Amended) The electronic component according to of claim 1 at least one of claims 1 to 22, in which wherein the at least one chip component (CB) comprises a housing comprising the (GE) having external contacts (AE).

24. (Currently Amended) The electronic component according to of claim 1 at least one of claims 1 to 23, in which wherein the at least one chip component (CB) is connected with to the multi-layer substrate via (MS) by means of wire bonding.

25. (Currently Amended) The electronic component according to of claim 1 at least one of claims 1 to 23, in which wherein the at least one chip component (CB) is connected with to the multi-layer substrate via (MS) by means of flip-chip technology.

26. (Currently Amended) Method for the production of the component according to at least one of claims 23 to 25, A method of producing an electronic component comprised of (i) a multi-layer substrate having an upper side and under side, the multi-layer substrate comprising at least one integrated impedance converter, and (ii) at least one chip component comprising external contacts, the method comprising the following steps:

[[ - ]] installation of a installing the at least one chip component in into a housing; and (GE);

[[ - ]] mounting of the housing onto a the upper side of the multi-layer substrate so as to electrically connect the at least one chip component to the integrated impedance converter (MS).

27. (Currently Amended) The method according to of claim 26, ~~wherein the~~  
further comprising:

mounting at least one discrete circuit element (~~SE~~) ~~is mounted~~ on the upper side of  
the multi-layer substrate (~~MS~~).

28. (Currently Amended) The method according to of claim 27, wherein the at  
least one chip component (~~CB~~) and the at least one discrete circuit element (~~SE~~) are  
attached to the upper side of the multi-layer substrate using a same attaching mechanism  
(~~MS~~) ~~in the same fashion~~.

29. (Currently Amended) The method of claim 27 ~~according to at least one of~~  
~~claims 26 to 28~~, wherein the at least one chip component (~~CB~~) ~~disposed on the upper side~~  
~~of the multi-layer substrate~~ and/or the at least one discrete circuit element (~~SE~~) is  
mechanically stabilized ~~with~~ using a casting compound.